

**IN THE CLAIMS**

Claims 1-13 (Canceled).

14 (Previously Presented). A method comprising:

forming a trench in an integrated circuit substrate;  
lining the trench with a catalyst material to remove gases from a circulating fluid;  
forming channels that align with said trench to allow fluid circulation completely  
across said substrate from one side of said substrate to the other and through said trench; and  
protecting said catalyst when forming said channels.

Claim 15 (Canceled).

16 (Original). The method of claim 14 including depositing platinum as said catalyst in said trench.

17 (Previously Presented). The method of claim 14 including depositing lead in said trench as said catalyst.

Claims 18-21 (Canceled).